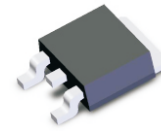


CMS16N06D-HF

N-Channel
RoHS Device
Halogen Free



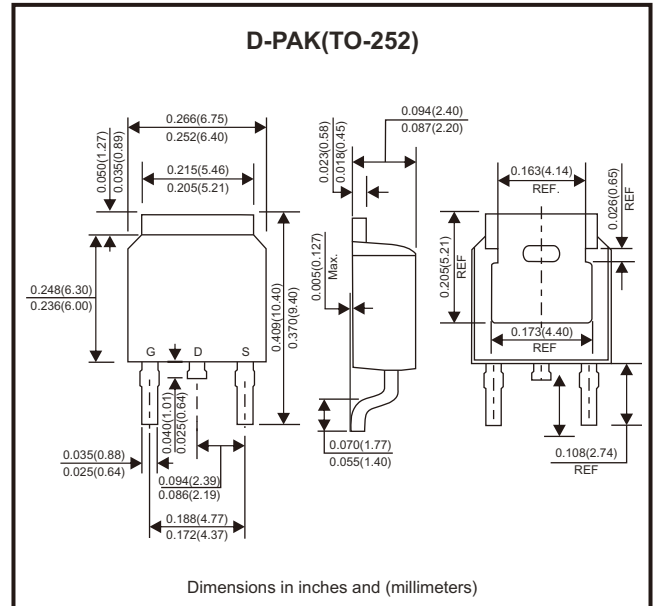
Features

- Low Reverse Transfer Capacitance
- High Switching Speed
- Improved dv/dt Capability
- 100% EAS Guaranteed
- Green Device Available

Description

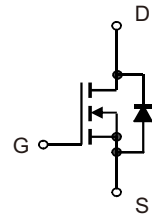
The CMS16N06D is the highest performance N-CH MOSFET with super high dense cell design for extremely low $R_{DS(on)}$ and gate charge for most of the synchronous buck converter applications.

The CMS16N06D meet the RoHS and green product requirement, 100% EAS guaranteed with full function reliability approved.



Circuit diagram

- G : Gate
- S : Source
- D : Drain



Maximum Ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D @ T_C=25^\circ\text{C}$	16	A
	$I_D @ T_C=100^\circ\text{C}$	10	A
Pulsed Drain Current ^{1,2}	$I_{DM} @ T_C=25^\circ\text{C}$	64	A
Continuous Drain Current	$I_D @ T_A=25^\circ\text{C}$	4.4	A
	$I_D @ T_A=70^\circ\text{C}$	3.5	A
Total Power Dissipation ⁴	$P_D @ T_C=25^\circ\text{C}$	27	W
	$P_D @ T_A=25^\circ\text{C}$	2	W
Single Pulse Avalanche Energy, $L=0.1\text{mH}^3$	E_{AS}	11	mJ
Single Pulse Avalanche Current, $L=0.1\text{mH}^3$	I_{AS}	15	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 ~ +150	$^\circ\text{C}$

Thermal Data

Parameter	Symbol	Conditions	Max. Value	Unit
Thermal Resistance Junction-ambient ¹	$R_{\theta JA}$	Steady State	62.5	$^\circ\text{C/W}$
Thermal Resistance Junction-case ¹	$R_{\theta JC}$	Steady State	4.6	$^\circ\text{C/W}$

Company reserves the right to improve product design , functions and reliability without notice.

REV:A

Electrical Characteristics (at T_J=25°C unless otherwise noted)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV _{DSS}	60	-	-	V	V _{GS} =0, I _D =250uA
Gate Threshold Voltage	V _{GS(th)}	1.0	1.8	2.5	V	V _{DS} =V _{GS} , I _D =250uA
Gate-Source Leakage Current	I _{GSS}	-	-	±100	nA	V _{GS} = ±20V
Drain-Source Leakage Current	I _{DSS}	-	-	1	uA	V _{DS} =60V, V _{GS} =0
Static Drain-Source On-Resistance ²	R _{DS(ON)}	-	37	50	mΩ	V _{GS} =10V, I _D =8A
		-	42	60		V _{GS} =4.5V, I _D =4A
Total Gate Charge ²	Q _g	-	14	-	nC	I _D =4A V _{DS} =30V V _{GS} =10V
Gate-Source Charge	Q _{gs}	-	2.9	-		
Gate-Drain ("Miller") Change	Q _{gd}	-	2.3	-		
Turn-on Delay Time ²	T _{d(on)}	-	3.9	-	ns	V _{DS} =30V I _D =1A V _{GS} =10V R _G =3.3Ω
Rise Time	T _r	-	13	-		
Turn-off Delay Time	T _{d(off)}	-	23	-		
Fall Time	T _f	-	6.7	-		
Input Capacitance	C _{iss}	-	815	-	pF	V _{GS} =0V V _{DS} =15V f=1.0MHz
Output Capacitance	C _{oss}	-	379	-		
Reverse Transfer Capacitance	C _{rss}	-	110	-		

Guaranteed Avalanche Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Single Pulse Avalanche Energy ⁵	EAS	3.2	-	-	mJ	V _{DD} =25V, L=0.1mH, I _{AS} =8A

Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage ²	V _{SD}	-	0.73	1.0	V	I _S =1A, V _{GS} =0V, T _J =25°C
Continuous Source Current ^{1,6}	I _S	-	-	16	A	---

Notes: 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.

3. The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=15A.

4. The power dissipation is limited by 150°C junction temperature.

5. The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

RATING AND CHARACTERISTIC CURVES

Typical Characteristics

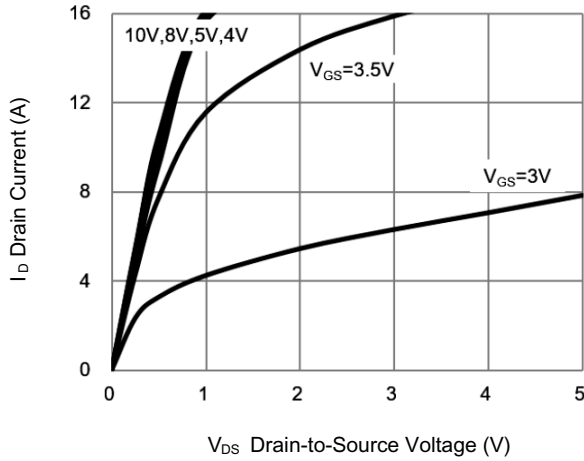


Fig.1 Typical Output Characteristics

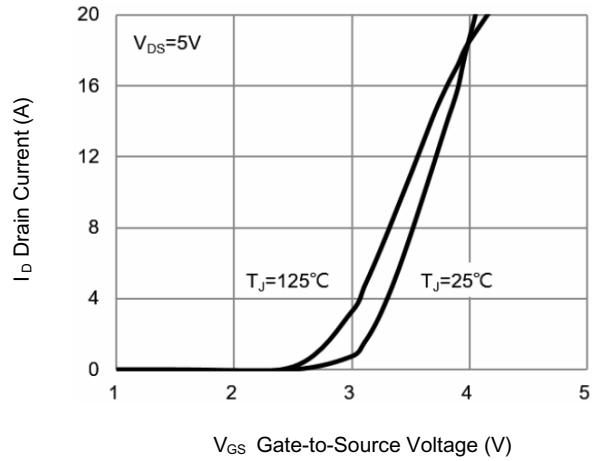


Fig.2 Transfer Characteristics

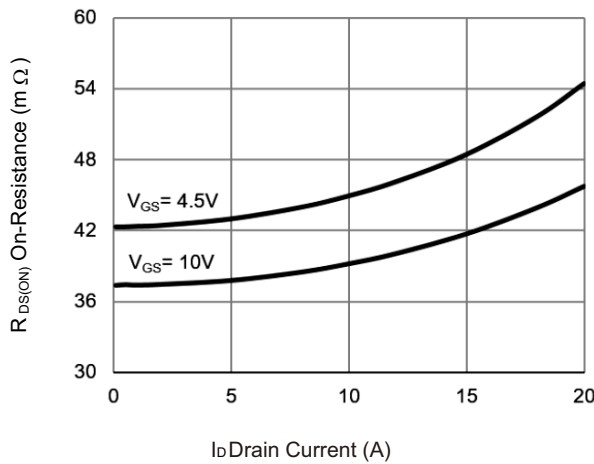


Fig.3 On-Resistance vs. Drain Current

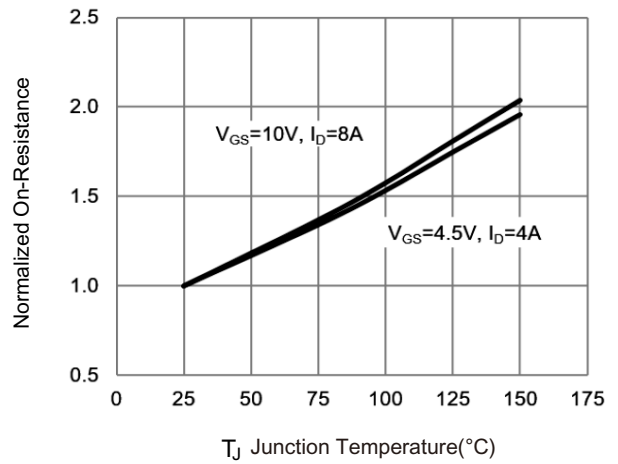


Fig.4 Normalized $R_{DS(on)}$ vs. T_J

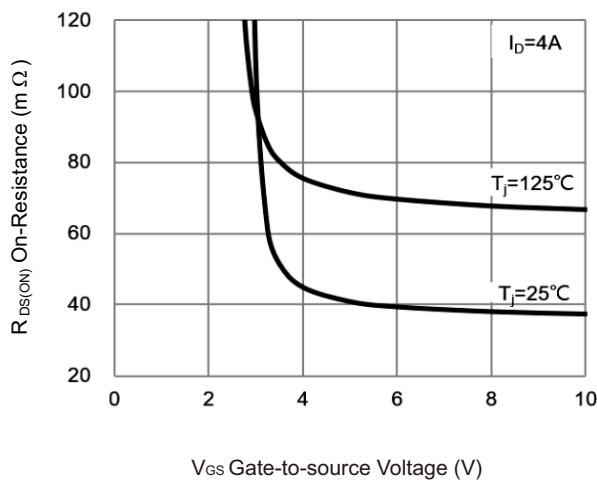


Fig.5 On-Resistance vs. G-S Voltage

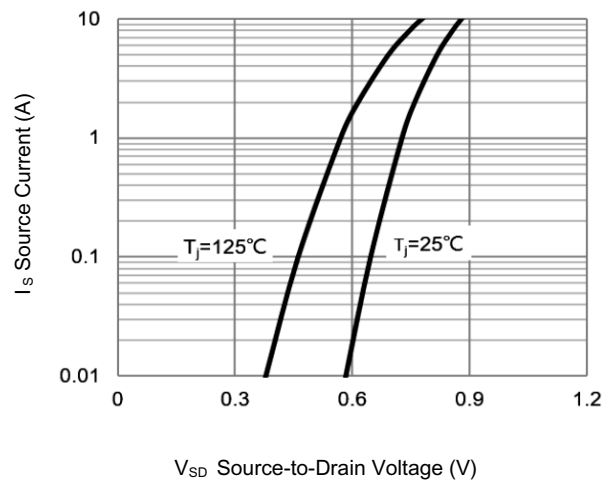


Fig.6 Forward Characteristics of Reverse

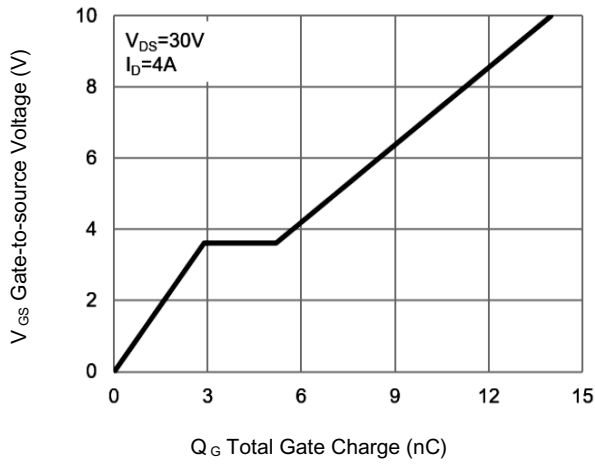


Fig.7 Gate Charge Characteristics

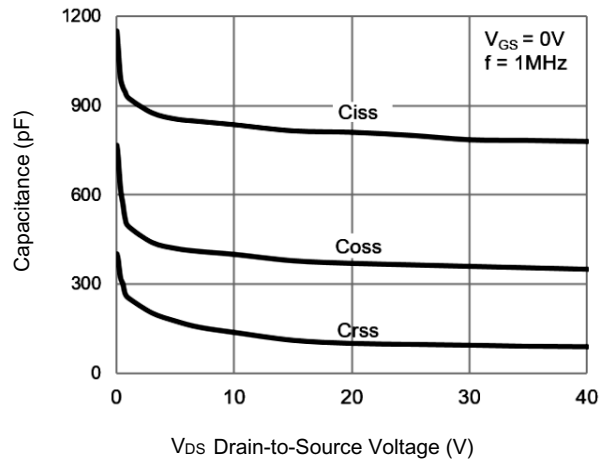


Fig.8 Capacitance Characteristics

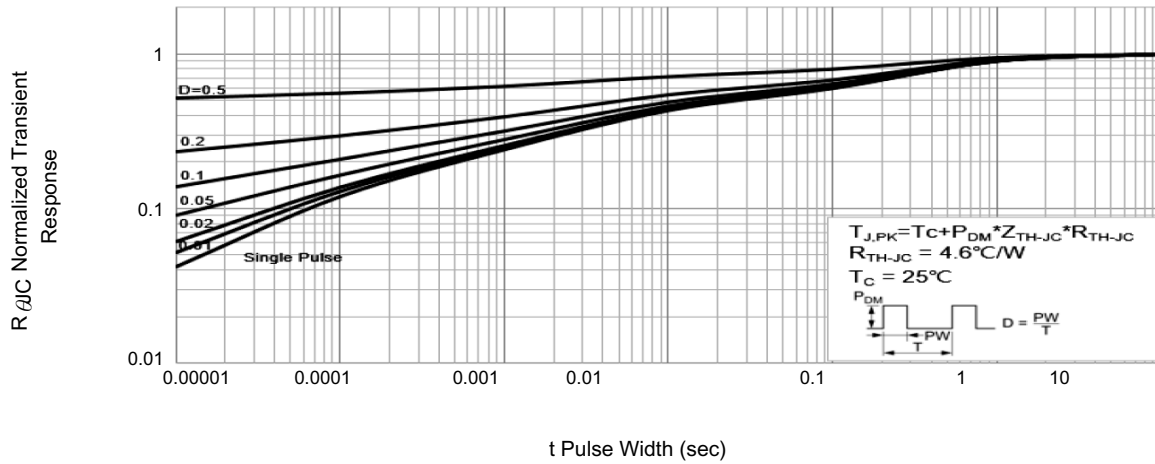


Fig.9 Normalized Maximum Transient Thermal Impedance

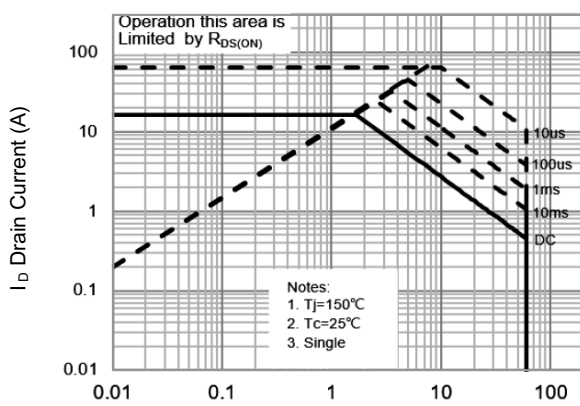


Fig.10 Safe Operating Area

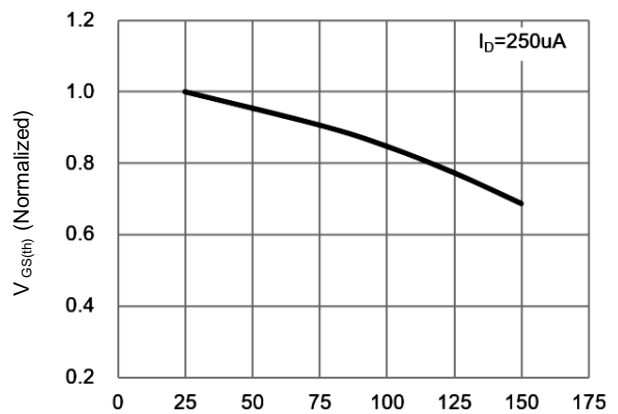
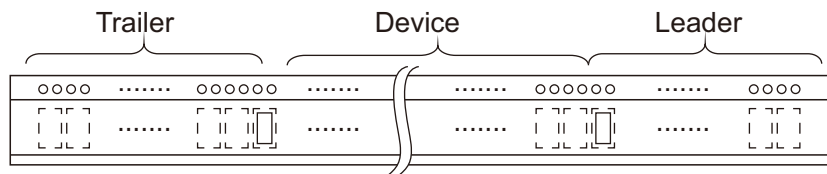
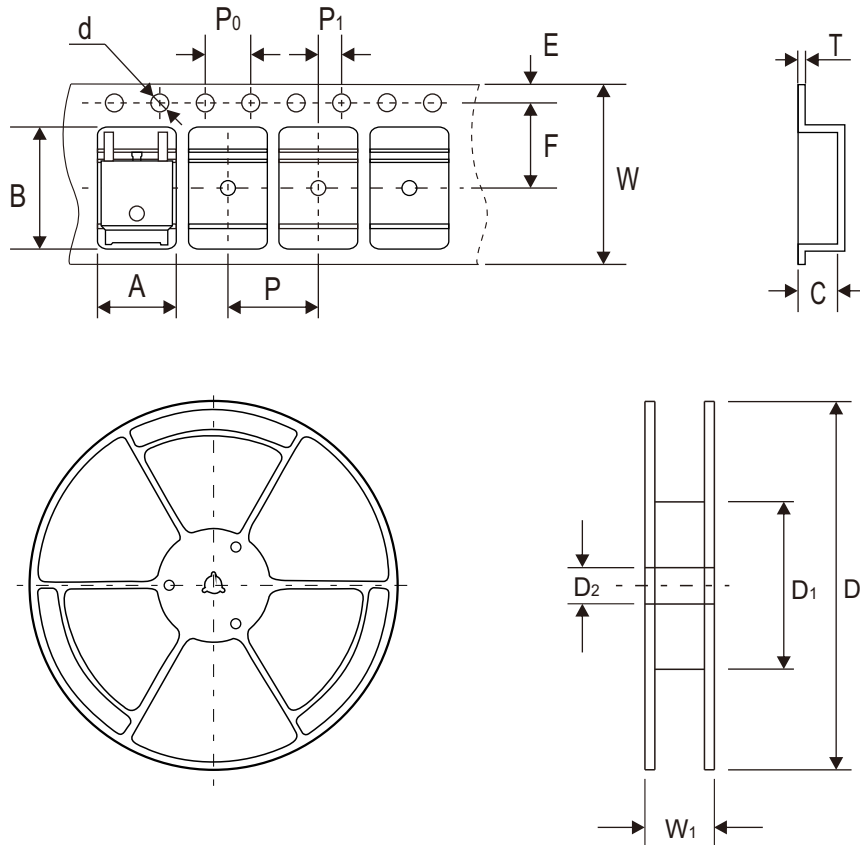


Fig.11 Normalized $V_{GS(th)}$ vs. Temperature

Reel Taping Specification



TO-252 (D-PAK)	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	6.90 ± 0.10	10.50 ± 0.10	2.70 ± 0.10	1.55 ± 0.05	330.00 ± 2.00	100.00 ± 2.00	13.00 ± 1.00
	(inch)	0.272 ± 0.004	0.413 ± 0.004	0.106 ± 0.004	0.061 ± 0.002	12.992 ± 0.079	3.937 ± 0.079	0.512 ± 0.039

TO-252 (D-PAK)	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	7.50 ± 0.10	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	0.30 ± 0.05	16.00 ± 0.10	21.00 ± 1.00
	(inch)	0.069 ± 0.004	0.295 ± 0.004	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	0.012 ± 0.002	0.630 ± 0.004	0.827 ± 0.039

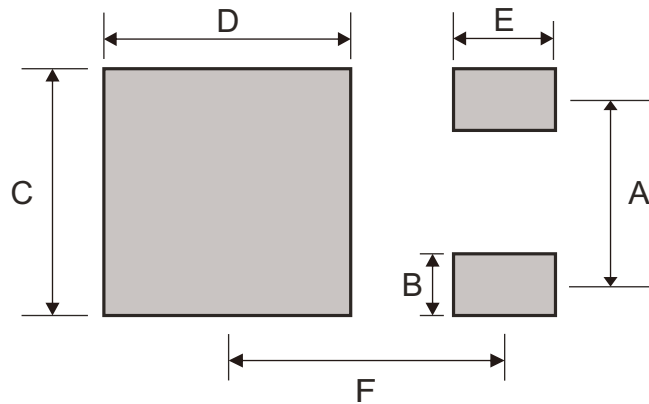
Marking Code

Part Number	Marking Code
CMS16N06D-HF	16N06A



Suggested PAD Layout

SIZE	TO-252 / DPAK	
	(mm)	(inch)
A	4.60	0.181
B	1.40	0.055
C	6.00	0.236
D	6.50	0.256
E	3.00	0.118
F	6.25	0.246



Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	REEL SIZE (inch)
TO-252/D-PAK	2,500	13